

What is claim d is:

1. An automatic package process for a card, comprising the steps of:

5 transferring a metal belt;
 stamping said metal belt to form a first and second
 metal shells without releasing from said metal belt;
 injection molding a first and second plastic frames on
 said first and second metal shells, respectively; and
10 combining said first and second plastic frames to form a
 case.

2. A process of claim 1, further comprising printing
patterns on said first and second metal shells after forming said
15 first and second plastic frames.

3. A process of claim 1, wherein said stamping for first
and second metal shells comprises forming a plurality of strips on
opposite sides of said metal shells.

20 4. A process of claim 3, further comprising bending said
strips for forming stakes.

5. A process of claim 1, further comprising stamping
25 said first metal shell for forming a bent extension.

6. A process of claim 4, wherein said first and second plastic frames embed said stakes on said first and second metal shells, respectively.

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7. A process of claim 5, wherein said second plastic frame embeds said bent extension of said second metal shell.

8. A process of claim 1, wherein said first and second plastic frames are combined together by sonic welding.

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9. A process of claim 1, wherein said metal belt is coated with an insulator film thereon.

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10. A process of claim 1, further comprising removing said first and second metal shells from said metal belt after injection molding said first and second plastic frames.

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11. A package for a small card with a thickness not larger than 3.3 mm, said package comprising:

first and second metal shells each having a thickness not larger than 0.15 mm, a plurality of stakes and an inner surface coated with an insulator film; and first and second plastic frames embedding said plurality of stakes, respectively, to form first and second half

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cases, said first plastic frame having a thickness
not larger than 0.7 mm, said second plastic frame
having a thickness not larger than 1.4 mm;
wherein said first and second plastic frames are
5 combined together to form a case.

12. A package of claim 11, wherein said first and second
plastic frames have a recess.

10 13. A package of claim 11, wherein said second plastic
frame has an I/O portion on which said second metal shell has a
bent extension embedded therewith.

14. A package of claim 11, wherein said first and second
15 plastic frames are combined by a glue.

15. A package of claim 11, wherein said first and second
plastic frames are combined by a sonic welding.

20 16. A package of claim 11, wherein said insulator film
comprises a Teflon.